



Description

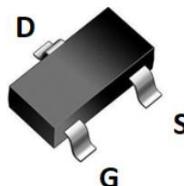
JMT N-channel MOSFET

Features

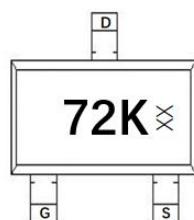
- $V_{DS}=60V$, $I_D=0.25A$
 $R_{DS(ON)} < 2.2\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)} < 2.87\Omega$ @ $V_{GS} = 5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired
- ESD Protected: 2KV

Application

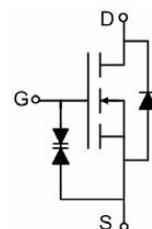
- Battery Operated Systems
- Direct logic-level Interface:
TTL/CMOS
- Solid-State Relays



SOT-23 top view



Marking and pin Assignment



Schematic diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
72K	JMTL2N7002KS	TAPING	SOT-23	7inch	3000	180000

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		60	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	0.25	A
		$T_A = 100^\circ C$	0.16	
I_{DM}	Pulsed Drain Current ^{note1}		1	A
P_D	Power Dissipation	$T_A = 25^\circ C$	0.23	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		543	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	60	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}$, $V_{GS}=0\text{V}$,	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm20\text{V}$	-	-	±10	μA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1	1.6	2.5	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$, $I_D=0.3\text{A}$	-	1.69	2.2	Ω
		$V_{GS}=4.5\text{V}$, $I_D=0.2\text{A}$	-	2.05	2.87	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	28	-	pF
C_{oss}	Output Capacitance		-	11	-	pF
C_{rss}	Reverse Transfer Capacitance		-	4	-	pF
Q_g	Total Gate Charge	$V_{DS}=10\text{V}$, $I_D=0.3\text{A}$, $V_{GS}=4.5\text{V}$	-	1.7	-	nC
Q_{gs}	Gate-Source Charge		-	0.3	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	0.6	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=30\text{V}$, $I_D=0.2\text{A}$, $R_{\text{GEN}}=10\Omega$, $V_{GS}=10\text{V}$	-	10	-	ns
t_r	Turn-on Rise Time		-	50	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	17	-	ns
t_f	Turn-off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	0.25	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	1	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=0.25\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Typical Performance Characteristics

Figure 1: Output Characteristics

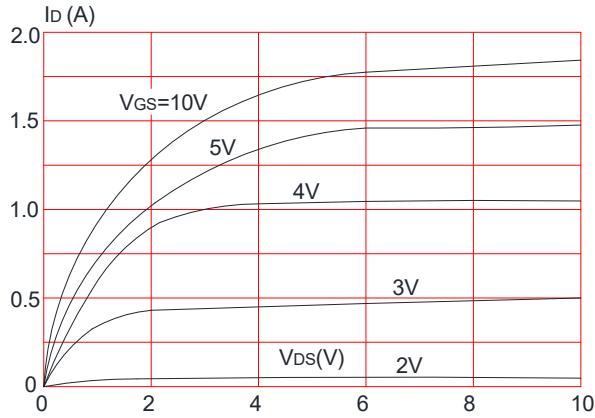


Figure 3: On-resistance vs. Drain Current

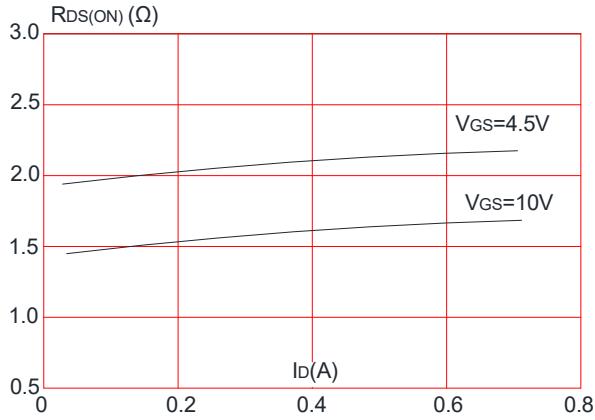


Figure 5: Gate Charge Characteristics

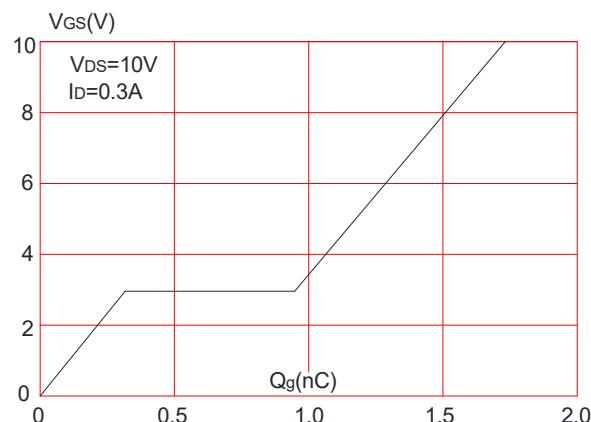


Figure 2: Typical Transfer Characteristics

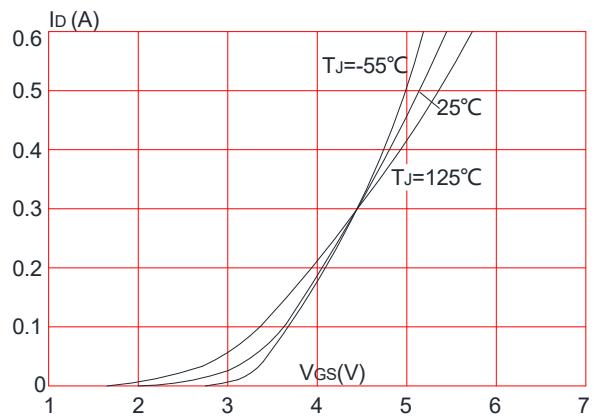


Figure 4: Body Diode Characteristics

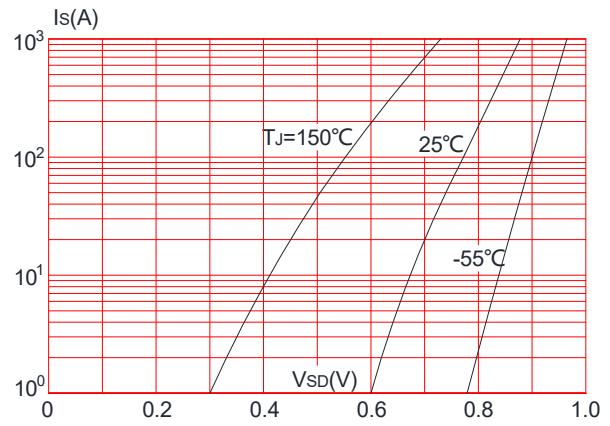


Figure 6: Capacitance Characteristics

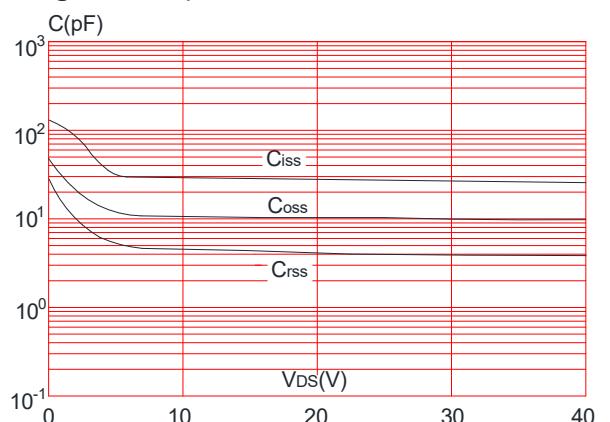


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

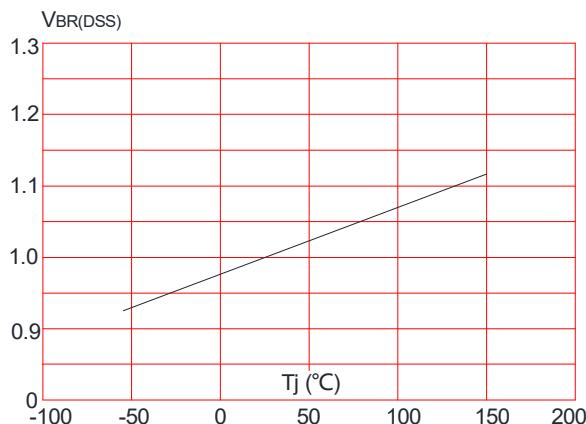


Figure 9: Maximum Safe Operating Area

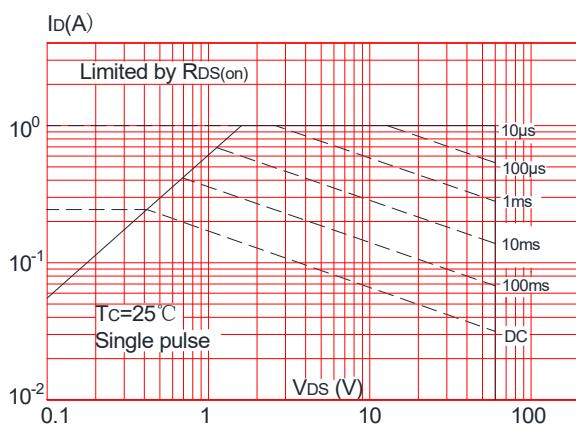


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

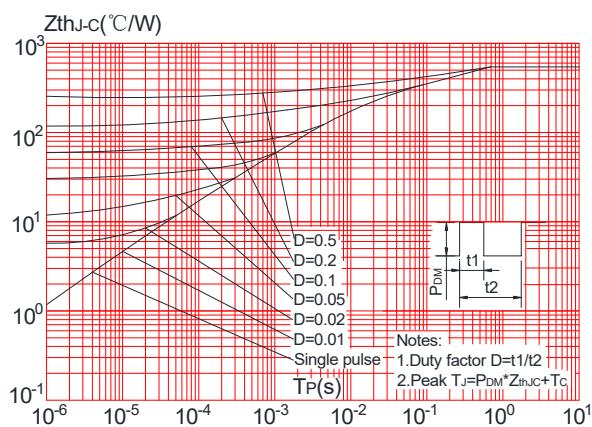


Figure 8: Normalized on Resistance vs. Junction Temperature

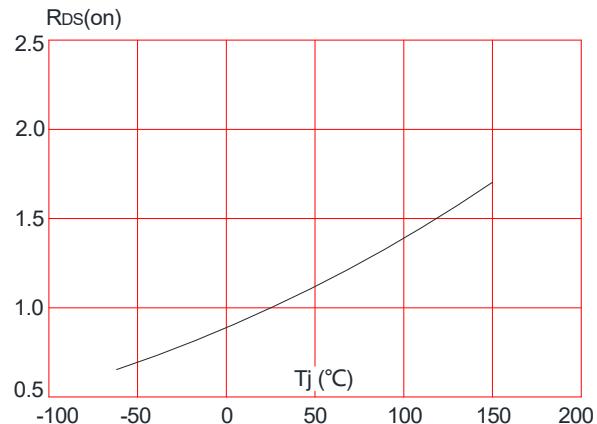
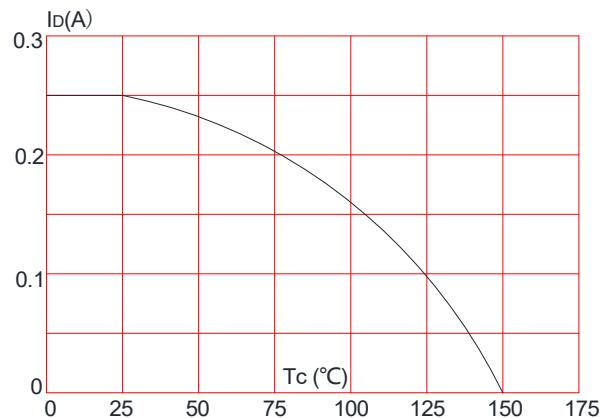


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Test Circuit

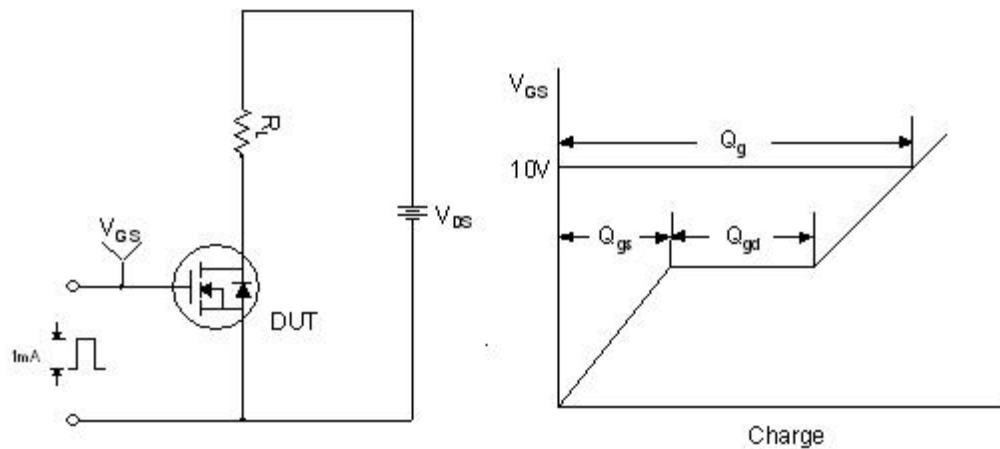


Figure 1. Gate Charge Test Circuit & Waveform

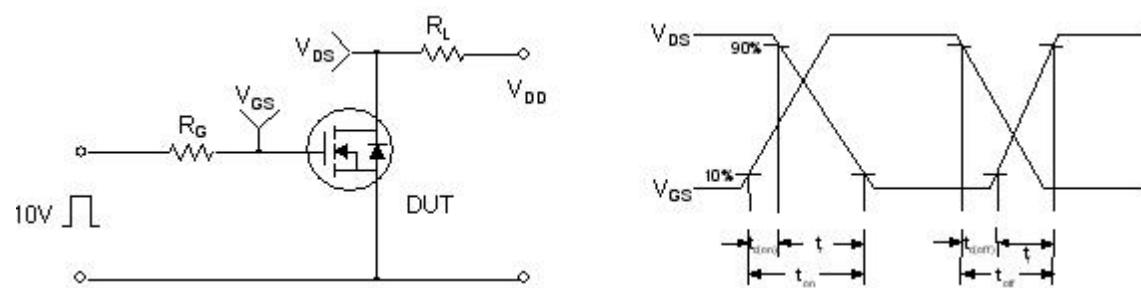


Figure 2. Resistive Switching Test Circuit & Waveforms

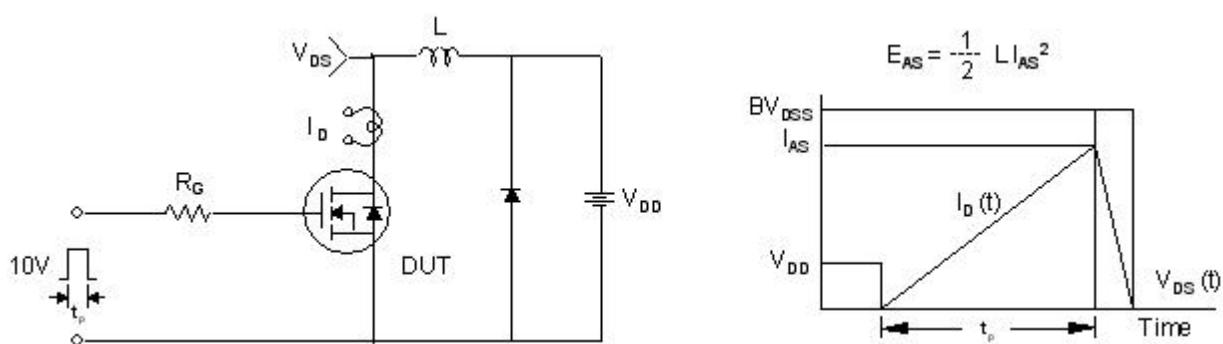
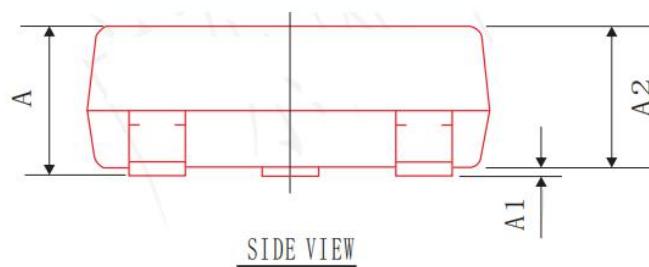
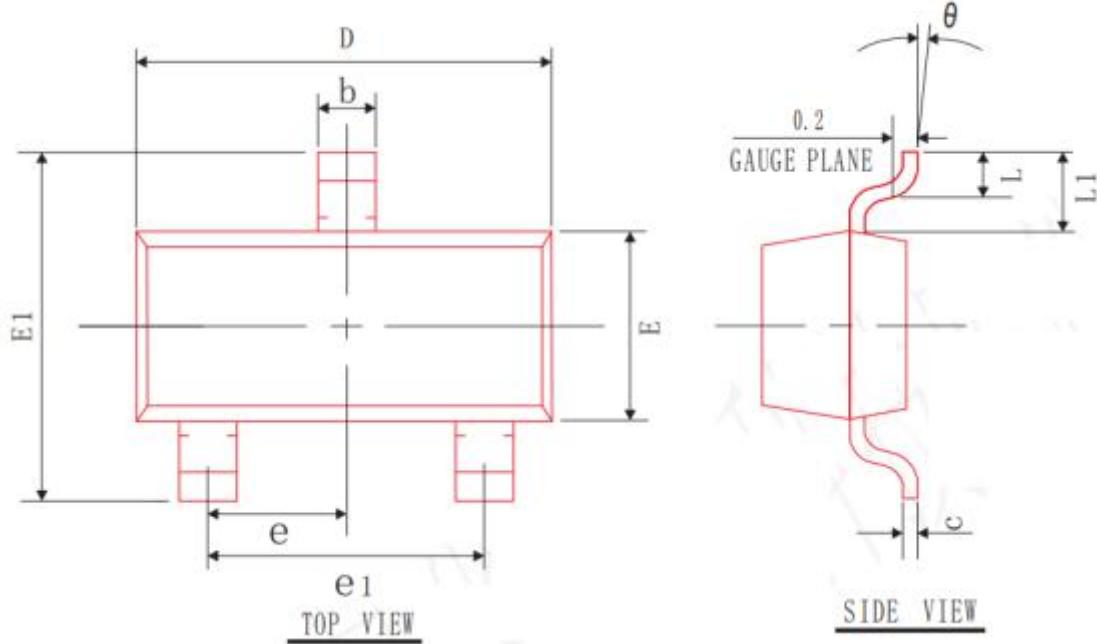


Figure 3. Unclamped Inductive Switching Test Circuit & Waveforms



Package Mechanical Data



SYMBOL	MIN	NOM	MAX
A	0.90	1.05	1.20
A ₁	0.00	0.05	0.10
A ₂	0.90	1.00	1.10
b	0.30	0.40	0.50
c	0.08	0.10	0.15
D	2.80	2.90	3.00
E	1.20	1.30	1.40
E ₁	2.30	2.40	2.50
L	0.30	0.40	0.50
θ	0°	5°	10°
L ₁	0.55 REF		
e	0.95 BSC		
e ₁	1.90 REF		



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